TFT DISPLAY SPECIFICATION

RAYSTAR

RAYSTAR Optronics, Inc. 曜凌光電股份有限公司



曜凌光電股份有限公司 Raystar Optronics, Inc.

42881台中市大雅區科雅路25號5樓 5F, No. 25, Keya Road, Daya Dist., Taichung City 42881, Taiwan T : +886-4-2565-0761 | F : +886-4-2565-0760 sales@raystar-optronics.com | www.raystar-optronics.com

RFI350U-AYW-MNN

SPECIFICATION

CUSTOMER:

APPROVED BY

PCB VERSION

DATE

FOR CUSTOMER USE ONLY

| SALES BY | APPROVED BY | CHECKED BY | PREPARED BY |
|----------|-------------|------------|-------------|
| | | | |
| | | | |
| | | | |

Release DATE:

TFT Display Inspection Specification: <u>https://www.raystar-optronics.com/download/products.htm</u> Precaution in use of TFT module: <u>https://www.raystar-optronics.com/download/declaration.htm</u>



Revision History

| VERSION | DATE | REVISED PAGE NO. | Note |
|---------|------------|------------------|-------------|
| 0 | 2022/01/24 | | First issue |
| | | | |
| | | | |



Contents

- 1.Module Classification Information
- 2.Summary
- **3.**General Specification
- 4.Interface
- 5.Contour Drawing
- 6.Block Diagram
- 7.Absolute Maximum Ratings
- **8.**Electrical Characteristics
- 9.Interface Timing
- **10.Optical Characteristics**
- 11.Reliability
- 12.Initial Code For Reference
- 13.Other



1.Module Classification Information

| R | F | I | 35 | 0U | - | Α | Y | W | - | Μ | N | N |
|---|---|---|----|----|---|---|---|---|---|---|----|----|
| 1 | 2 | 3 | 4 | 5 | - | 6 | 7 | 8 | - | 9 | 10 | 11 |

| Item | | Description | | | | | | |
|------|--|--|--|--|--|--|--|--|
| 1 | R : Raystar Opt | R : Raystar Optronics Inc. | | | | | | |
| 2 | Display Type:I | \rightarrow TFT Type, J \rightarrow Custom TFT | Ċ | | | | | |
| 3 | Solution: A: 128 F:800x K:1280 P:640x | 480 G:640x480 H:1024x600 I: x800 L:240x400 M:1024x768 N | :480x234 E:480x272 320x480 J:240x320 I:128x128 O:480x800 :800x320 | | | | | |
| 4 | Display Size : 3 | .5" TFT | | | | | | |
| 5 | Version Code. | | ý | | | | | |
| 6 | Model Type:6A : TFT LCD6 : TFT+FRE : TFT+FR+CONTROL BOARDH : TFT+D/V BOARDJ : TFT+FR+A/D BOARDI : TFT+FR+D/V BOARDN : TFT+FR+A/D BOARD+CONTROLB : TFT+POWER BDBOARDS : TFT+FR+POWER BOARD (DC TO DC)1 : TFT+CONTROLBOARD | | | | | | | |
| 7 | Polarizer Type, Temperature range, View direction | Polarizer Type, emperature range, ew direction $I \rightarrow Transmissive, W. T, 6:00 ; C \rightarrow Transmissive, N. T, 6:00$ $L \rightarrow Transmissive, W. T, 12:00 ; F \rightarrow Transmissive, N. T, 12:00$ $Y \rightarrow Transmissive, W. T, IPS TFT ;$ $A \rightarrow Transmissive, N. T, IPS TFT$ $Z \rightarrow Transmissive, W. T, O-TFT$ $R \rightarrow Transmissive, Super W. T, O-TFT$ $N \rightarrow Transmissive, Super W. T, 6:00;$ $Q \rightarrow Transmissive, Super W. T, 12:00$ | | | | | | |
| 8 | Backlight | $V \rightarrow$ Transmissive, Super W.T, VA TFTW : LED, WhiteF : CCFL, White | | | | | | |
| 9 | Driver Method | D: Digital A: Analog L : LVDS I | M:MIPI | | | | | |
| 10 | Interface | N : without control board A : 8Bit S:SPI Interface R: RS232 U:USI | | | | | | |
| 11 | TS | N : Without TS S : resistive touch panel | | | | | | |



.

2.Summary

TFT 3.5 is a IPS transmissive type color active matrix TFT liquid crystal display that use amorphous silicon TFT as switching devices. This module is a composed of a TFT_LCD module, It is usually designed for industrial application and this module follows RoHs.



3.General Specification

- Size: 3.5 inch
- Dot Matrix: 320 x RGBx 480(TFT) dots
- Module dimension: 54.5 (W) x83.0 (H) x 2.46(D) mm
- Active area: 48.96 x 73.44 mm
- Pixel pitch: 0.153 × 0.153 mm
- LCD type: TFT, Normally Black, Transmissive
- View Direction: 80/80/80/80
- Aspect Ratio: Portrait
- TFT Driver IC: ILI9488 or Equivalent
- TFT Interface: 1-Lane MIPI
- Backlight Type: LED,Normally White
- With /Without TP: Without TP
- Surface: Anti-Glare

*Color tone slight changed by temperature and driving voltage.

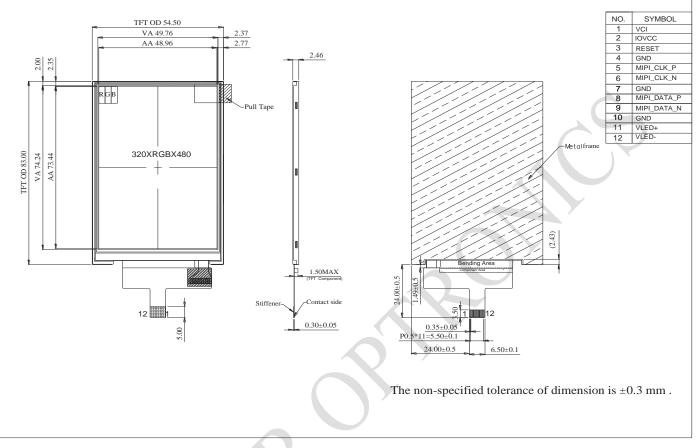


4.1. LCM PIN Definition

| NO | Symbol | Function | I/O |
|----|-------------|---|-----|
| 1 | VCI | A supply voltage to the analog circuit. Connect to an external power supply of 2.5 ~ 3.3V. Connect to a stabilizing capacitor between VCI and GND. | Ρ |
| 2 | IOVCC | A supply voltage to the digital circuit. Connect to an external power supply of 1.65 ~ 3.3V. | |
| 3 | RESET | Reset input signal Initialize the chip with a low input. Be sure to execute a power-on reset after supplying power. | I |
| 4 | GND | Ground | I |
| 5 | MIPI_CLK_P | Positive polarity of low voltage differential clock signal Leave the pin open when not in use. | Ι |
| 6 | MIPI_CLK_N | Negative polarity of low voltage differential clock signal Leave the pin open when not in use | I |
| 7 | GND | Ground | I |
| 8 | MIPI_DATA_P | Positive polarity of low voltage differential data signal Leave the pin open when not in use. | I |
| 9 | MIPI_DATA_N | Negative polarity of low voltage differential data signal Leave the pin open when not in use. | I |
| 10 | GND | Ground | Ι |
| 11 | VLED+ | Anode of LED backlight. | |
| 12 | VLED- | Cathode of LED backlight | |

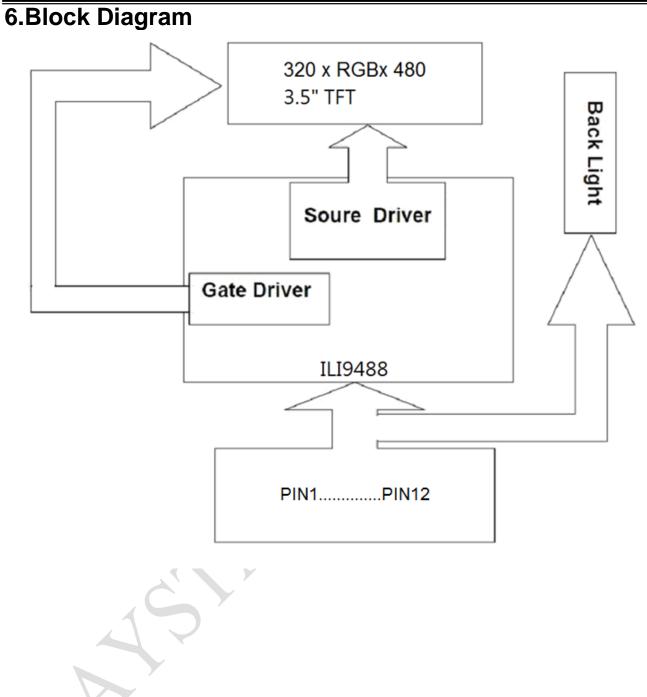


5.Contour Drawing











7.Absolute Maximum Ratings

| Item | Symbol | Min | Тур | Max | Unit |
|-----------------------|--------|-----|-----|-----|------|
| Operating Temperature | TOP | -20 | | +70 | |
| Storage Temperature | TST | -30 | _ | +80 | |

Note: Device is subject to be damaged permanently if stresses beyond those absolute maximum ratings listed above

1. Temp. □60□, 90% RH MAX. Temp. >60□, Absolute humidity shall be less than 90% RH at 60□



8.Electrical Characteristics 8.1. Operating conditions:

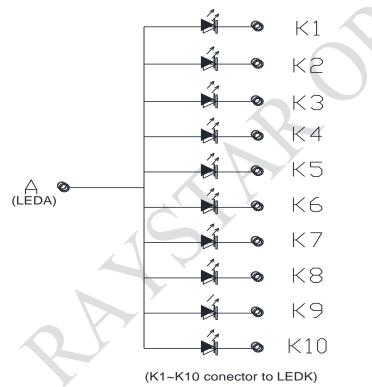
| | | | | 1 | | 1 |
|------------------------------|--------|------------------------|-----|---------|-----|------|
| ltem | Symbol | Condition | Min | Тур | Max | Unit |
| Supply Voltage for digital | IOVCC | _ | _ | 1.8/2.8 | 3.3 | V |
| Supply Voltage for analog | VCI | _ | _ | 2.8 | 3.3 | V |
| Power Supply for TFT Current | ICC | IOVCC=VCI =VCC=3.3V | _ | 13.6 | | mA |

8.2. LED driving conditions

| Parameter | Symbol | Min | Тур | Max | Unit | Remark |
|---------------|--------|-----|-------|-----|------|----------|
| LED current | _ | — | 160 | | mA | _ |
| LED voltage | LEDA | 2.7 | 3.2 | 3.4 | V | Note 1 |
| LED Life Time | _ | — | 50000 | | Hr | Note 2,3 |

Note 1 : There are 1 Groups LED

Note 2 : Ta = 25°C



Note 3 : Brightness to be decreased to 50% of the initial value



9.Interface Timing

9.1. General Description

The MIPI-DSI is enabled or disabled by the external IM [2:0] pin.

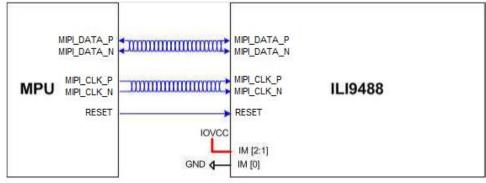


Figure 1: DSI System Interface Diagram

The communication is separated into two different levels between the MCU and the display module:

*Low level communication is done on the interface level.

*High level communication is done on the packet level.

9.2. Interface Level Communication

6.2.1 General

The display module uses data and clock lane differential pairs for DSI. Both differential lane pairs can be driven to Low Power (LP) or High Speed (HS) mode. Low Power mode means that each line of the differential pair is used in the single ended mode, and a differential receiver is disable (the termination resistor of the receiver is disable), and it can be driven into a low power mode. High Speed mode means that differential pairs (the termination resistor of the receiver is enable) are not used in the single ended mode. Different modes and protocols are used in each mode when information is to be transferred from the MCU to the display module and vice versa. The State Codes of the High Speed (HS) and Low Power (LP) lane pair are defined below.

| Lana Daia Stata Carda | Line DC Voltage Levels | | High Speed (HS) | Low Power | | |
|-----------------------|------------------------|-----------|------------------|--------------|-------------|--|
| Lane Pair State Code | | | Burst Mode | Control Mode | Escape Mode | |
| HS-0 | Low (HS) | High (HS) | Differential – 0 | Note 1 | Note1 | |
| HS-1 | High (HS) | Low (HS) | Differential – 1 | Note 1 | Note 1 | |
| LP-00 | Low (LP) | Low (LP) | Not Defined | Bridge | Space | |
| LP-01 | Low (LP) | High (LP) | Not Defined | HS – Request | Mark – 0 | |
| LP-10 | High (LP) | Low (LP) | Not Defined | LP – Request | Mark – 1 | |
| LP-11 | High (LP) | High (LP) | Not Defined | Stop | Note 2 | |

Notes:

1. Low-Power Receivers (LP-Rx) of the lane pair will check the LP-00 state code, when the Lane Pair is in the High Speed (HS) mode.



2. If Low-Power Receivers (LP-Rx) of the lane pair recognizes LP-11 state code, the lane pair will return to LP-11 of the Control Mode.

6.2.2.MIPI_CLK Lanes

MIPI_CLK_P/N lanes can be driven into three different power modes:

*Low Power Mode (LPM)

*Ultra Low Power Mode (ULPM)

*High Speed Clock Mode (HSCM)

Clock lanes are in the single ended mode (LP = Low Power) when entering or leaving the Low Power Mode (LPM) or Ultra Low Power Mode (ULPM). Clock lanes are in the single ended mode (LP = Low Power) when entering or leaving the High Speed Clock Mode (HSCM). These entering and leaving protocols use clock lanes in the single ended mode to generate an entering or leaving sequence. The principal flow chart of the different clock lanes power modes is illustrated below.

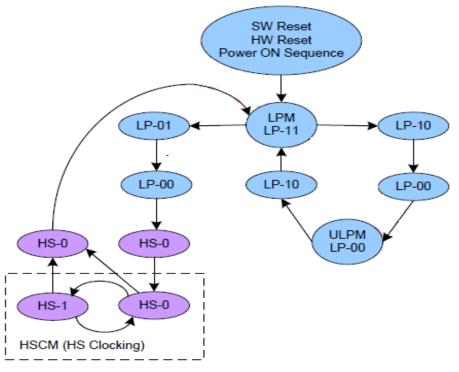


Figure 2: Clock Lanes Power Mode

6.2.2.1. Low Power Mode (LPM)

MIPI_CLK_P/N lanes can be driven to the Low Power Mode (LPM), when MIPI_CLK lanes enter the LP-11

State Code, in three different ways:

(1) After SW Reset, HW Reset or Power On Sequence => LP-11

(2) After MIPI_CLK_P/N lanes leave the Ultra Low Power Mode (ULPM, LP-00 State Code) => LP-10 => LP-11 (LPM).

This sequence is illustrated below.



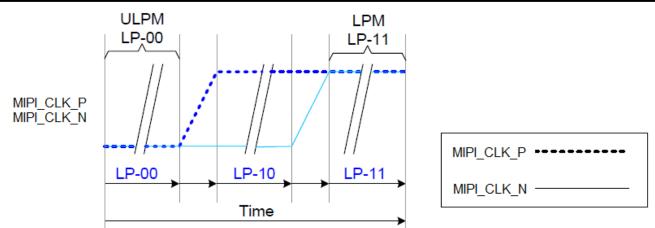


Figure 3: From ULPM to LPM

(3) After MIPI_CLK_P/N lanes leave the High Speed Clock Mode (HSCM, HS-0 or HS-1 State Code) => HS-0 => LP-11 (LPM). This sequence is illustrated below.

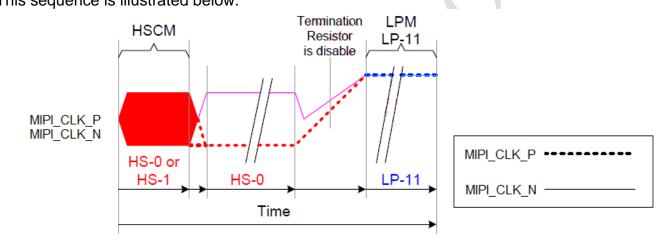


Figure 4: From High Speed Clock Mode (HSCM) to LPM



All changes of the three modes are illustrated in the flow chart below.

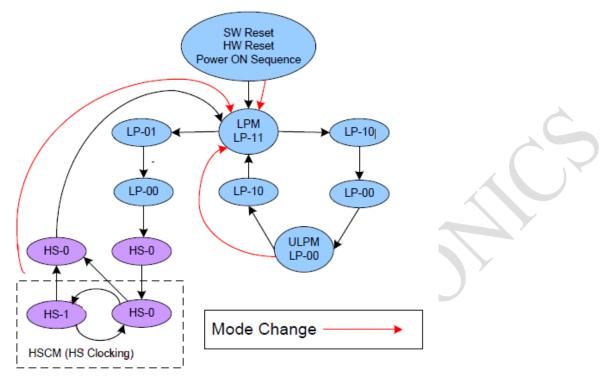
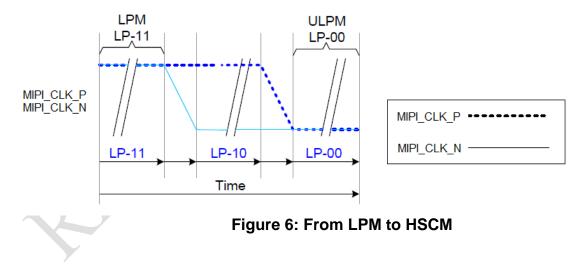


Figure 5: All Changes of the Three Modes to LPM

6.2.2.2 Ultra Low Power Mode (ULPM)

MIPI_CLK_P/N lanes can be driven to the Ultra Low Power Mode (ULPM) when MIPI_CLK lanes enter the LP-00 State Code. The only possibility is from the Low Power Mode (LPM, LP-11 State Code) => LP-10 => LP-00 (ULPM). This sequence is illustrated below.





The mode change is also illustrated below.

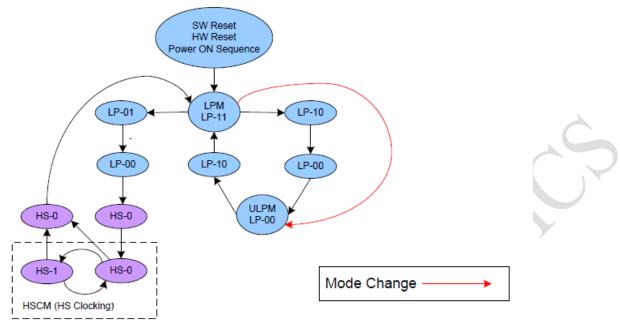


Figure 7: Mode Change from LPM to ULPM

6.2.2.3. High-Speed Clock Mode (HSCM)

MIPI_CLK_P/N lanes can be driven to the High Speed Clock Mode (HSCM), when MIPI_CLK lanes start to work between HS-0 and HS-1 State Codes. The only entering possibility is from the Low Power Mode (LPM, LP-11 State Code) => LP-01 => LP-00 => HS-0 => HS-0/1 (HSCM). This sequence is illustrated below

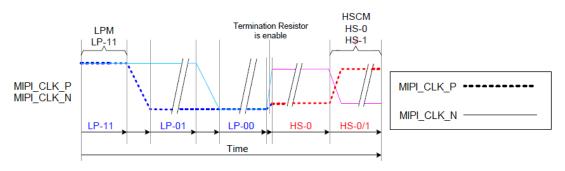


Figure 8: From LPM to HSCM

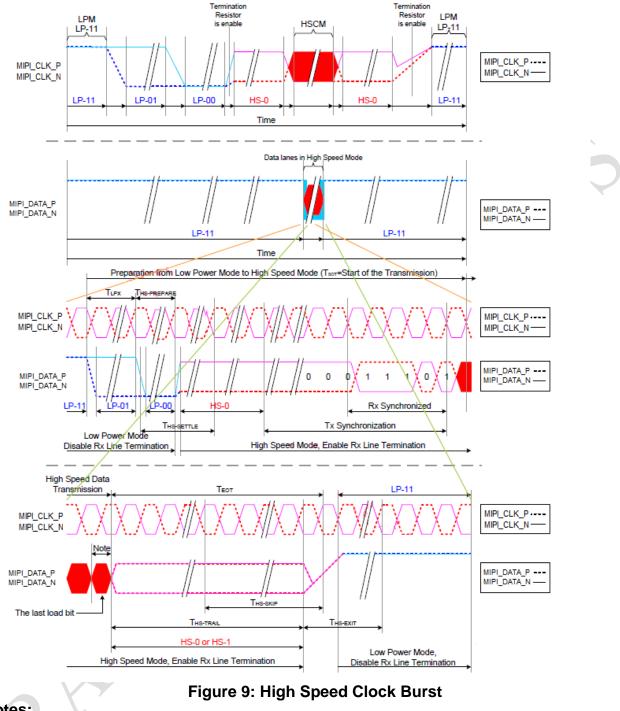
The high speed clock (MIPI_CLK_P/N) starts before high speed data is sent via MIPI_DATA_P/N lanes. The high speed clock continues clocking after the high speed data sending has been stopped. The burst of the high speed clock consists of: *Even number of transitions

*Even number of transition

*Start state is HS-0

*End state is HS-0

RFI350U-AYW-MNN



Notes:

- 1. If the last load bit is HS-0, the transmitter changes from HS-0 to HS-1.
- 2. If the last load bit is HS-1, the transmitter changes from HS-1 to HS-0.

9.3. Reset Timing

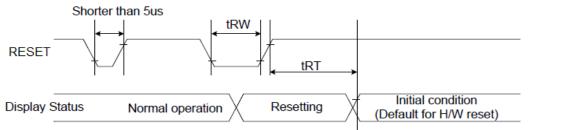


Table 2: Reset Timing

| Signal | Symbol | Parameter | Min | Мах | Unit |
|--------|------------------|----------------------|------------------|--------------|------|
| | tRW | Reset pulse duration | 10 | | uS |
| RESET | tRT Reset cancel | | | 5 (note 1,5) | mS |
| | | | 120 (note 1,6,7) | mS | |

Notes:

1. The reset cancel also includes the required time for loading ID bytes, VCOM setting and other settings from the EEPROM to registers. After a rising edge of RESX, this loading is done within 5 ms after the H/W reset cancel (tRT).

2. According to the Table 40, a spike due to an electrostatic discharge on the RESX line does not cause irregular system reset.

| RESET Pulse | Action |
|---------------------|----------------|
| Shorter than 5us | Reset Rejected |
| Longer than 9us | Reset |
| Between 5us and 9us | Reset starts |

3. During the Reset period, the display will be blanked (When Reset starts in the Sleep Out mode, the display will enter the blanking sequence in at least 120 ms. The display remains the blank state in the Sleep In mode.) and then return to the default condition for the Hardware Reset.

4. Spike Rejection can also be applied during a valid reset pulse, as shown below:

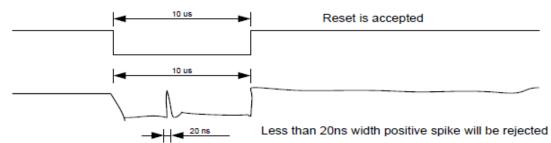


Figure 10: Positive Noise Pulse during Reset Low

- 5. When Reset is applied during the Sleep In Mode.
- 6. When Reset is applied during the Sleep Out Mode.

7. It is necessary to wait 5msec after releasing RESX before sending commands. The Sleep Out command also cannot be sent in 120msec.

9.4. Other command, display data format, Please reference the ILI9488 Spec.



10.Optical Characteristics

| ltem | | Symbol | Condition. | Min | Тур. | Max. | Unit | Remark |
|-----------------------|-------|----------|----------------------------------|--------------|------|--------------|-------|----------------------|
| Response tim | ne | Tr Tf | θ=0° 、Φ=0° | - | 30 | - | .ms | Note 3, |
| Contrast ratio | D | CR | At optimized viewing angle | - | 700 | - | - | Note 4, |
| Color Chromaticity | White | Wx Wy | θ=0°、Φ=0 | 0.26 0.28 | 0.31 | 0.36 0.38 | | Note 2,6,7 |
| | | ΘR | | - | 80 | - | | _,,,, |
| | Hor. | ΘL | CR≧10 | - | 80 | - | Deg | Note 1 |
| Viewing angle | Ver. | ΦT | CR≡10 | - | 80 | - | Deg. | |
| | vei. | ΦВ | | - | 80 | | | |
| Brightness | | - | - | 500 | 600 | | cd/m2 | Center of display |
| Uniformity | | (U) | - | 75 | - | | % | Note5 |

Ta=25±2℃ (ILED=160mA)

Note 1: Definition of viewing angle range

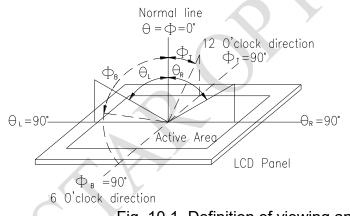
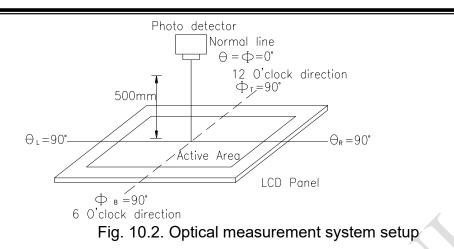


Fig. 10.1. Definition of viewing angle

Note 2: Test equipment setup:

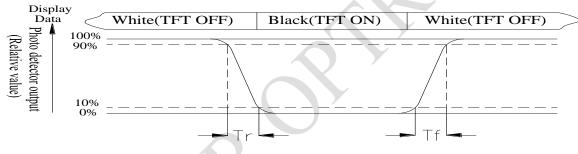
After stabilizing and leaving the panel alone at a driven temperature for 10 minutes, the measurement should be executed. Measurement should be executed in a stable, windless, and dark room. Optical specifications are measured by Topcon BM-7 luminance meter 1.0° field of view at a distance of 50cm and normal direction.





Note 3: Definition of Response time:

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time, Tr, is the time between photo detector output intensity changed from 90% to 10%. And fall time, Tf, is the time between photo detector output intensity changed from 10% to 90%



Note 4: Definition of contrast ratio:

The contrast ratio is defined as the following expression.

Contrast ratio (CR) = $\frac{\text{Luminance measured when LCD on the "White" state}}{\text{Luminance measured when LCD on the "Black" state}}$



Note 5: Definition of Luminance Uniformity Active area is divided into 9 measuring areas (reference the picture in below). Every measuring point is placed at the center of each measuring area. Luminance Uniformity (U) = Lmin/Lmax x100% L = Active area length

W = Active area width

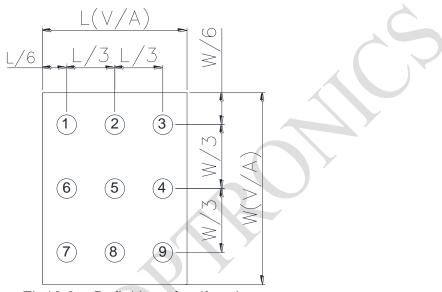


Fig10.3. . Definition of uniformity

Note 6: Definition of color chromaticity (CIE 1931) Color coordinates measured at the center point of LCD

Note 7: Measured at the center area of the panel when all the input terminals of LCD panel are electrically opened.

Page 22, Total 27 Pages



11.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

| Environmental Tes | t | | |
|-------------------------|--|--------------------------------|------|
| Test Item | Content of Test | Test Condition | Note |
| High Temperature | Endurance test applying the high storage | 80 ℃ | 2 |
| storage | temperature for a long time. | 96hrs | |
| Low Temperature | Endurance test applying the low storage | -30℃ | 1,2 |
| storage | temperature for a long time. | 96hrs | |
| High Temperature | Endurance test applying the electric stress | 70 ℃ | |
| Operation | (Voltage & Current) and the thermal stress to the element for a long time. | 96hrs | |
| Low Temperature | Endurance test applying the electric stress | -20 ℃ | 1 |
| Operation | under low temperature for a long time. | 96hrs | |
| High Temperature/ | The module should be allowed to stand at 40 | 40℃,90%RH | 1,2 |
| Humidity Operation | ℃,90%RH max | 96hrs | |
| Thermal shock | The sample should be allowed stand the | -20 ℃/70℃ | |
| resistance | following 10 cycles of operation | 10 cycles | |
| | -20℃ 25℃ 70℃ | | |
| | | | |
| | 30min 5min 30min | | |
| | 1 cycle | | • |
| Vibration test | Endurance test applying the vibration during | Total fixed | 3 |
| | transportation and using. | amplitude : 1.5mm Vibration | |
| | | Frequency : | |
| | | 10~55Hz | |
| | | One cycle 60 | |
| | | seconds to 3 | |
| | | directions of X,Y,Z | |
| | | for Each 15 minutes | |
| Static electricity test | Endurance test applying the electric stress to | VS=±600V(contact) | |
| | the terminal. | ,±800v(air), | |
| | | RS=330Ω | |
| | | CS=150pF | |
| | | 10 times | |

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



{

12.Initial Code For Reference Void ILI9488 Panel InitialCode(void)

WriteComm(0xE0); WriteData(0x0D); WriteData(0x13); WriteData(0x14); WriteData(0x01); WriteData(0x0C); WriteData(0x03); WriteData(0x31); WriteData(0x46); WriteData(0x45); WriteData(0x03): WriteData(0x0C); WriteData(0x0A): WriteData(0x2A); WriteData(0x30); WriteData(0x0D); WriteComm(0xE1); WriteData(0x0A); WriteData(0x10); WriteData(0x16); WriteData(0x05); WriteData(0x12); WriteData(0x08); WriteData(0x3D); WriteData(0x45); WriteData(0x53); WriteData(0x07); WriteData(0x11); WriteData(0x0E); WriteData(0x30); WriteData(0x33); WriteData(0x0A);

WriteComm(0xC0); WriteData(0x0A); //VERG12=4.187 WriteData(0x0A);

WriteComm(0xC1); //VGH=VCIx6, VGL=-VCIx4 WriteData(0x41);

WriteComm(0xC5); WriteData(0x00); //VCOM WriteData(0x25); WriteData(0x80);



}

WriteComm(0x36); WriteData(0x08); // BGR=1 //MY=0,MX=0 WriteComm(0x3A); WriteData(0x77); //(0x66):16bit,(0x77):18bit WriteComm(0xF8); WriteData(0x05); //dither on WriteComm(0xB1); WriteData(0xA0); WriteData(0x11); WriteComm(0xB4); WriteData(0x02); WriteComm(0xB6); WriteData(0x82); WriteData(0x22); WriteData(0x3B); WriteComm(0xE9); WriteData(0x01); WriteComm(0xF7); WriteData(0xA9); WriteData(0x51); WriteData(0x2C); WriteData(0x82); WriteComm(0x21); WriteData(0x00); WriteComm(0x11); delay1(120); WriteComm(0x29); delay1(20);



Page: 1

| | LCM Sample | e Estimate Feedback Sheet |
|---------------------------------|---------------|---------------------------|
| Module Number : | | |
| 1 · Panel Specification | | |
| 1. Panel Type : | Pass | □ NG , |
| 2. View Direction : | Pass | □ NG , |
| 3. Numbers of Dots : | Pass | □ NG , |
| 4. View Area : | Pass | □ NG , |
| 5. Active Area : | Pass | □ NG , |
| 6.Operating Temperature : | Pass | □ NG , |
| 7.Storage Temperature : | Pass | □ NG , |
| 8.Others : | | |
| 2 · Mechanical Specification : | | |
| 1. PCB Size : | □ Pass | □ NG , |
| 2.Frame Size : | Pass | □ NG , |
| 3.Materal of Frame : | Pass | □ NG , |
| 4.Connector Position : | Pass | □ NG , |
| 5.Fix Hole Position : | Pass | □ NG , |
| 6.Backlight Position : | Pass | □ NG , |
| 7. Thickness of PCB : | Pass | □ NG , |
| 8. Height of Frame to PCB : | Pass | □ NG , |
| 9.Height of Module : | Pass | □ NG , |
| 10.Others : | Pass | □ NG , |
| 3 · <u>Relative Hole Size</u> : | | |
| 1.Pitch of Connector : | Pass | □ NG , |
| 2.Hole size of Connector : | Pass | □ NG , |
| 3.Mounting Hole size : | Pass | □ NG , |
| 4.Mounting Hole Type : | Pass | □ NG , |
| 5.Others : | Pass | □ NG , |
| 4 · Backlight Specification : | | |
| 1.B/L Type : | Pass | □ NG , |
| 2.B/L Color : | Pass | □ NG , |
| 3.B/L Driving Voltage (Refere | nce for LED T | ype): □ Pass □ NG , |
| 4.B/L Driving Current : | Pass | □ NG , |
| 5.Brightness of B/L : | Pass | □ NG , |
| 6.B/L Solder Method : | Pass | □ NG , |
| 7.Others : | Pass | □ NG , |

>> Go to page 2 <<



Page: 2

| Module Number : | | |
|--------------------------------|-------------|--------|
| 5 · Electronic Characteristics | of Module : | |
| 1.Input Voltage : | Pass | □ NG , |
| 2.Supply Current : | Pass | □ NG , |
| 3.Driving Voltage for LCD : | Pass | □ NG , |
| 4.Contrast for LCD : | Pass | □ NG , |
| 5.B/L Driving Method : | Pass | □ NG , |
| 6.Negative Voltage Output : | □ Pass | □ NG , |
| 7.Interface Function : | Pass | □ NG , |
| 8.LCD Uniformity : | Pass | □ NG , |
| 9.ESD test : | □ Pass | □ NG , |
| 10.Others : | Pass | □ NG , |
| 0.0 | . | |

6 · <u>Summary</u> :

| Sales signature : | |
|----------------------|--|
| Customer Signature : | |

|--|